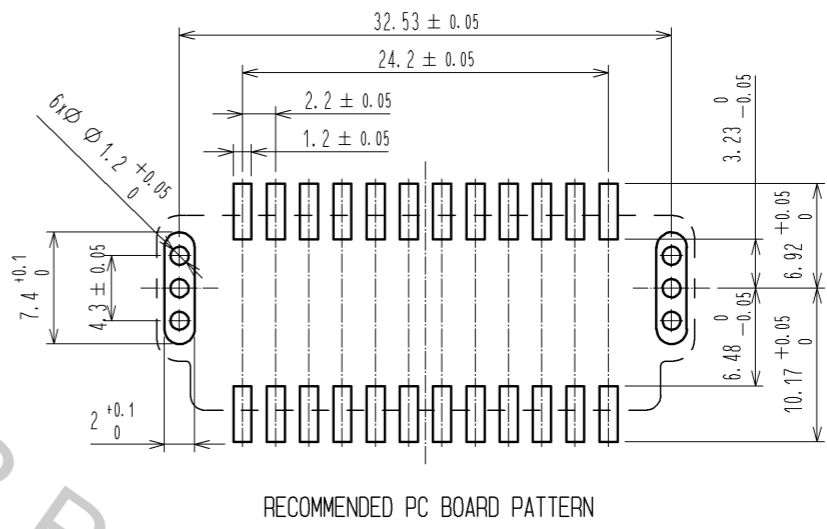
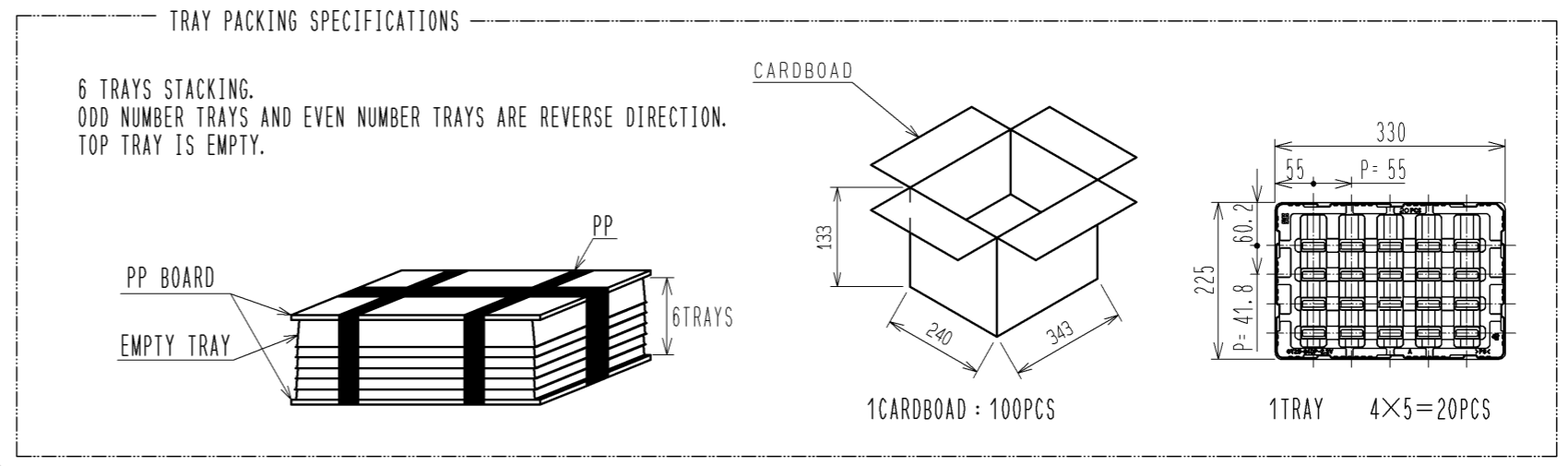
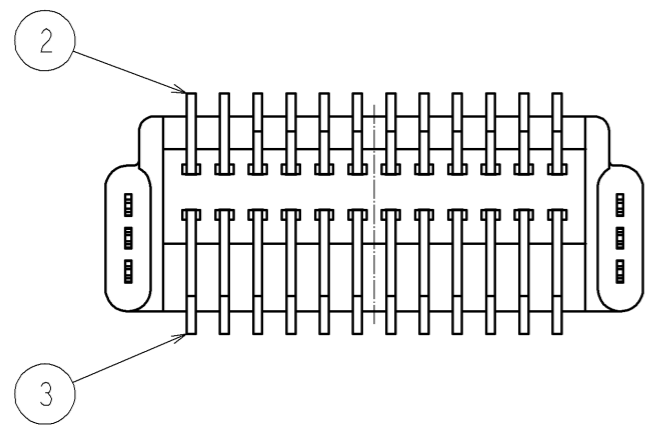
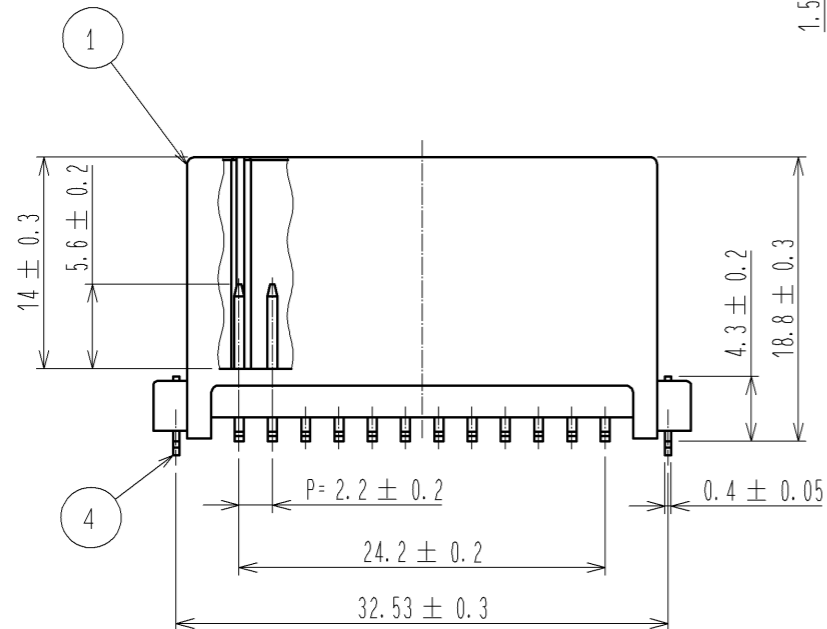
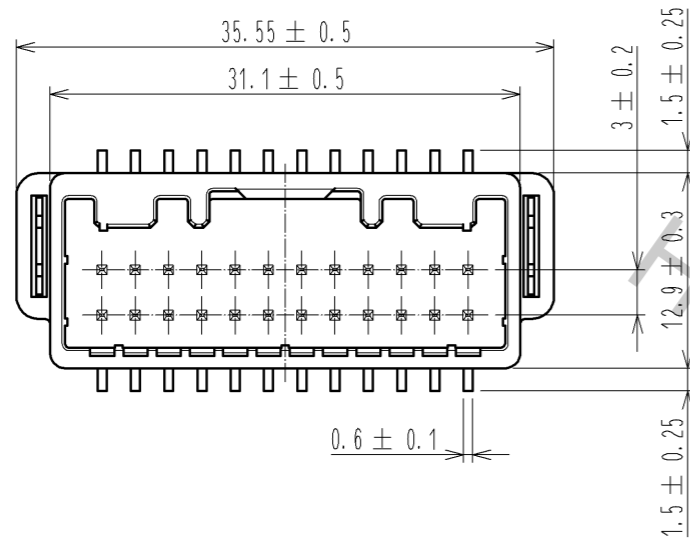
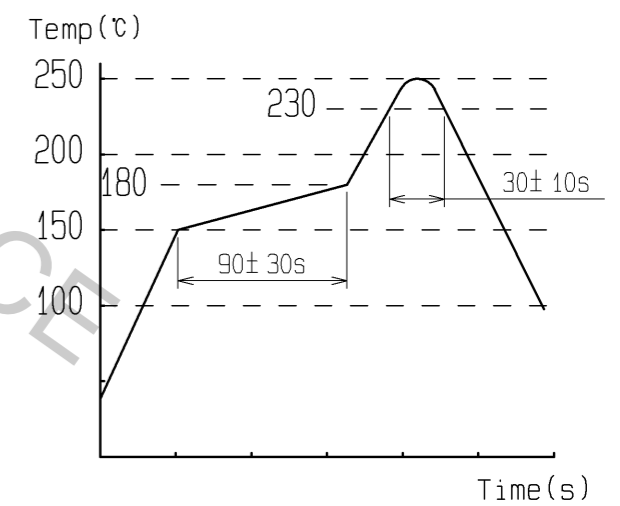


ELV, RoHS COMPLIANT

A
B
C
D
E
F



NOTE1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
USED REFLOW SYSTEM : IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 MAX
PEAK : 250°C
OVER 230°C : 20~40s
PREHEAT : 150~180°C
60~120s
2. TEMPERATURE FOR SOLDERING IRON : 280~300°C WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1 MAX.
4. PC BOARD THICKNESS=1.6.
5. RECOMMENDED SOLDER THICKNESS=0.15



2	BRASS	TIN PLATED	T=0.64	4	BRASS	TIN PLATED	T=0.4	
1	PPS	LIGHT GRAY		3	BRASS	TIN PLATED	T=0.64	
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS	
UNITS	mm	SCALE	2 : 1	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HIROSE ELECTRIC CO., LTD.		APPROVED	AR. SHIRAI	12.07.31	DRAWING NO. EDC3-166657-01			
		CHECKED	NH. NAKATA	12.07.30	PART NO. GT25-24DP-2. 2V(C01)			
		DESIGNED	TK. SHISHIKURA	12.07.30	CODE NO. CL775-0021-0-01			
		DRAWN	TK. SHISHIKURA	12.07.30	1/1			